

1.5V Drive Pch+SBD MOSFET

ES6U1

●Structure

Silicon P-channel MOSFET /
Schottky barrier diode

●Features

- 1) Pch MOSFET and schottky barrier diode are put in WEMT6 package.
- 2) High-speed switching, Low On-resistance.
- 3) Low voltage drive (1.5V drive).
- 4) Built-in Low V_F schottky barrier diode.

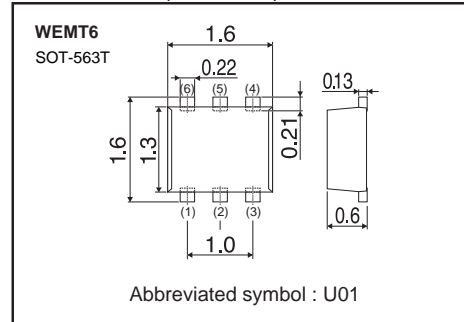
●Application

Switching

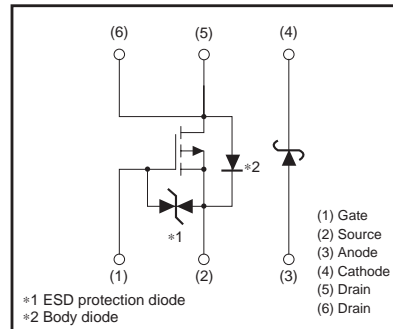
●Packaging specifications

Type	Package	Taping
	Code	T2R
	Basic ordering unit (pieces)	8000
ES6U1		○

●Dimensions (Unit : mm)



●Inner circuit



●Absolute maximum ratings (Ta=25°C)

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Parameter	Symbol	Limits	Unit	
Drain-source voltage	V_{DSS}	-12	V	
Gate-source voltage	V_{GSS}	±10	V	
Drain current	Continuous	I_D	±1.3	A
	Pulsed	I_{DP} *1	±2.6	A
Source current (Body diode)	Continuous	I_S	-0.5	A
	Pulsed	I_{SP} *1	-2.6	A
Channel temperature	T_{ch}	150	°C	
Power dissipation	P_D *2	0.7	W / ELEMENT	

*1 $P_w \leq 10\mu s$, Duty cycle $\leq 1\%$
*2 Mounted on a ceramic board

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Parameter	Symbol	Limits	Unit
Repetitive peak reverse voltage	V_{RM}	25	V
Reverse voltage	V_R	20	V
Forward current	I_F	0.5	A
Forward current surge peak	I_{FSM} *1	2.0	A
Junction temperature	T_j	150	°C
Power dissipation	P_D *2	0.5	W / ELEMENT

*1 60Hz · 1cycle
*2 Mounted on a ceramic board

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Parameter	Symbol	Limits	Unit
Power dissipation	P_D *	0.8	W / TOTAL
Range of storage temperature	T_{stg}	-55 to +150	°C

* Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

<MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	–	–	±10	μA	V _{GS} = ±10V, V _{DS} =0V
Drain-source breakdown voltage	V _{(BR) DSS}	–12	–	–	V	I _D = –1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	–	–	–1	μA	V _{DS} = –12V, V _{GS} =0V
Gate threshold voltage	V _{GS(th)}	–0.3	–	–1.0	V	V _{DS} = –6V, I _D = –1mA
Static drain-source on-state resistance	R _{DS(on)} *	–	190	260	mΩ	I _D = –1.3A, V _{GS} = –4.5V
		–	280	390	mΩ	I _D = –0.6A, V _{GS} = –2.5V
		–	400	600	mΩ	I _D = –0.6A, V _{GS} = –1.8V
		–	530	1060	mΩ	I _D = –0.2A, V _{GS} = –1.5V
Forward transfer admittance	Y _{fs} *	1.4	–	–	S	V _{DS} = –6V, I _D = –1.3A
Input capacitance	C _{iss}	–	290	–	pF	V _{DS} = –6V
Output capacitance	C _{oss}	–	28	–	pF	V _{GS} = 0V
Reverse transfer capacitance	C _{rss}	–	21	–	pF	f= 1MHz
Turn-on delay time	t _{d(on)} *	–	8	–	ns	V _{DD} = –6V
Rise time	t _r *	–	10	–	ns	I _D = –0.6A
Turn-off delay time	t _{d(off)} *	–	30	–	ns	V _{GS} = –4.5V
Fall time	t _f *	–	9	–	ns	R _L = 10Ω
Total gate charge	Q _g *	–	2.4	–	nC	V _{DD} = –6V R _L = 4.6Ω
Gate-source charge	Q _{gs} *	–	0.6	–	nC	I _D = –1.3A R _G = 10Ω
Gate-drain charge	Q _{gd} *	–	0.4	–	nC	V _{GS} = –4.5V

*Pulsed

<MOSFET> Body diode (Source-drain)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _{SD} *	–	–	–1.2	V	I _S = –1.3A, V _{GS} =0V

*Pulsed

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Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _F	–	–	0.36	V	I _F = 0.1A
		–	–	0.52	V	I _F = 0.5A
Reverse current	I _R	–	–	100	μA	V _R = 20V

●Electrical characteristics curves

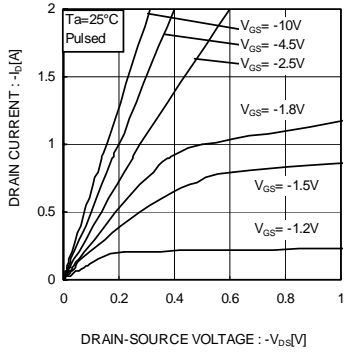


Fig.1 Typical Output Characteristics (I)

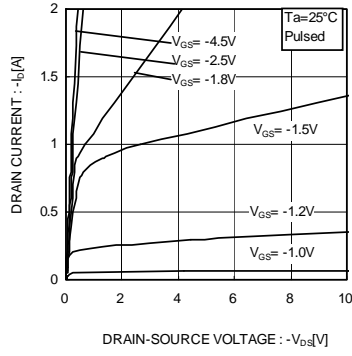


Fig.2 Typical Output Characteristics (II)

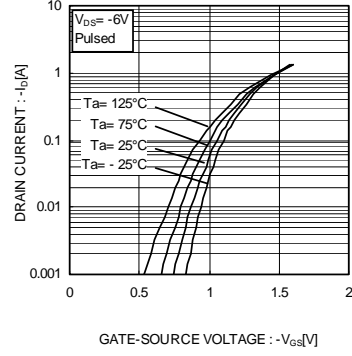


Fig.3 Typical Transfer Characteristics

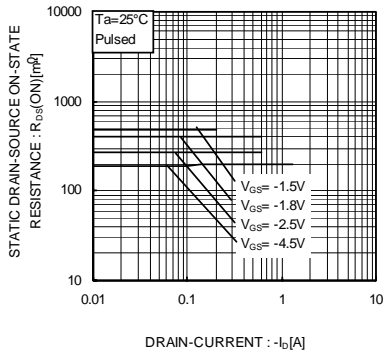


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current (I)

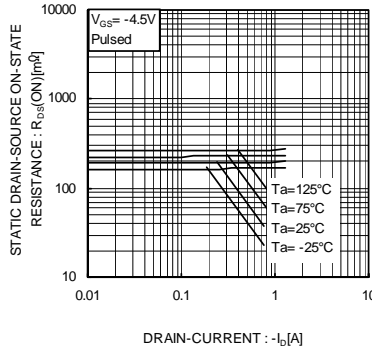


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current (II)

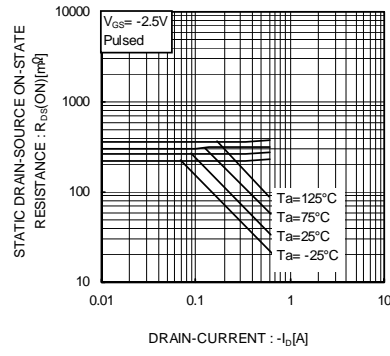


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current (III)

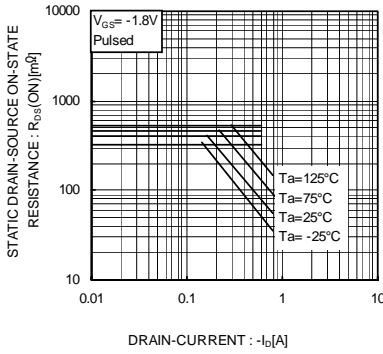


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (IV)

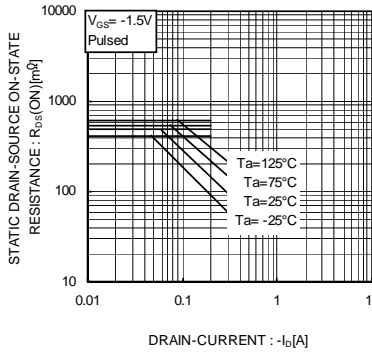


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (V)

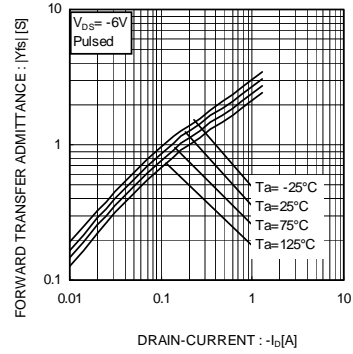


Fig.9 Forward Transfer Admittance vs. Drain Current

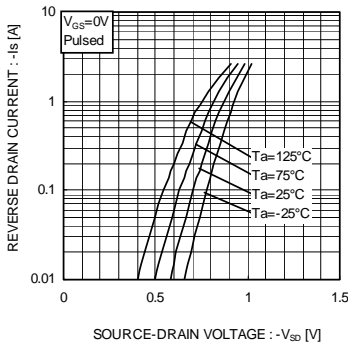


Fig.10 Reverse Drain Current vs. Source-Drain Voltage

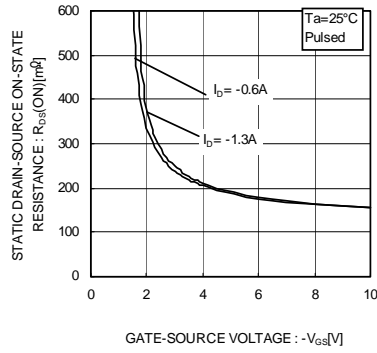


Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

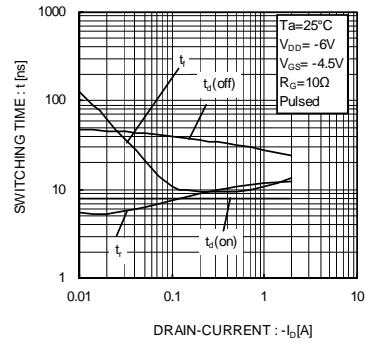


Fig.12 Switching Characteristics

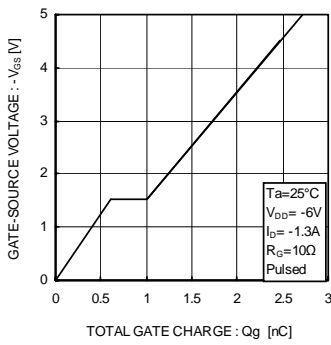


Fig.13 Dynamic Input Characteristics

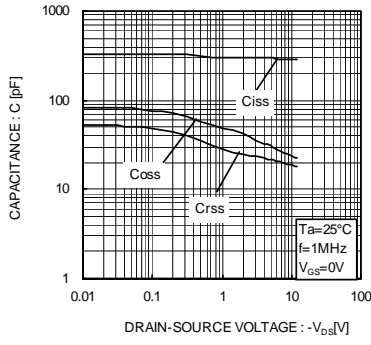


Fig.14 Typical Capacitance vs. Drain-Source Voltage

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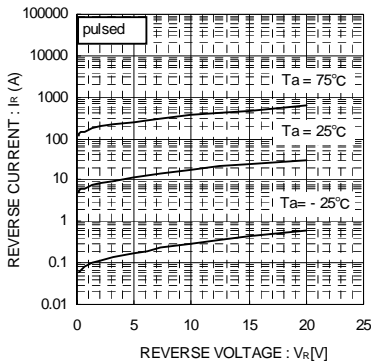


Fig.1 Reverse Current vs. Reverse Voltage

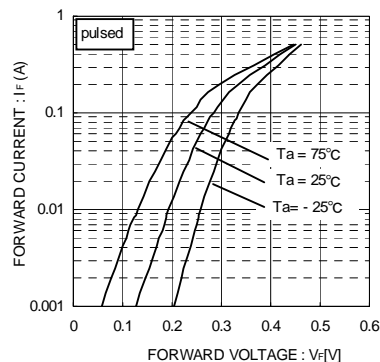


Fig.2 Forward Current vs. Forward Voltage

●Measurement circuits

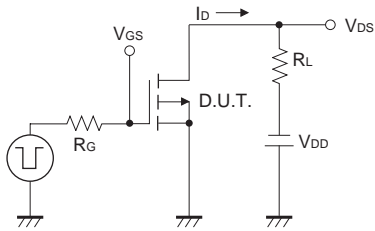


Fig.1-1 Switching Time Measurement Circuit

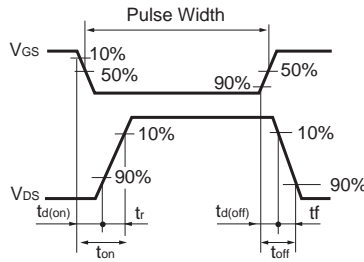


Fig.1-2 Switching Waveforms

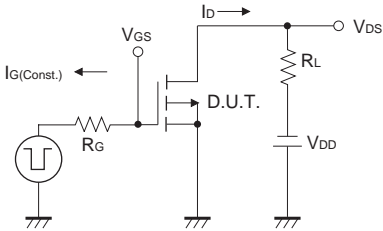


Fig.2-1 Gate Charge Measurement Circuit

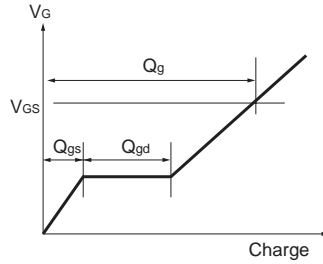


Fig.2-2 Gate Charge Waveform

●Notice

1. SBD has a large reverse leak current compared to other type of diode. Therefore; it would raise a junction temperature, and increase a reverse power loss. Further rise of inside temperature would cause a thermal runaway. This built-in SBD has low V_F characteristics and therefore, higher leak current. Please consider enough the surrounding temperature, generating heat of MOSFET and the reverse current.
2. This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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